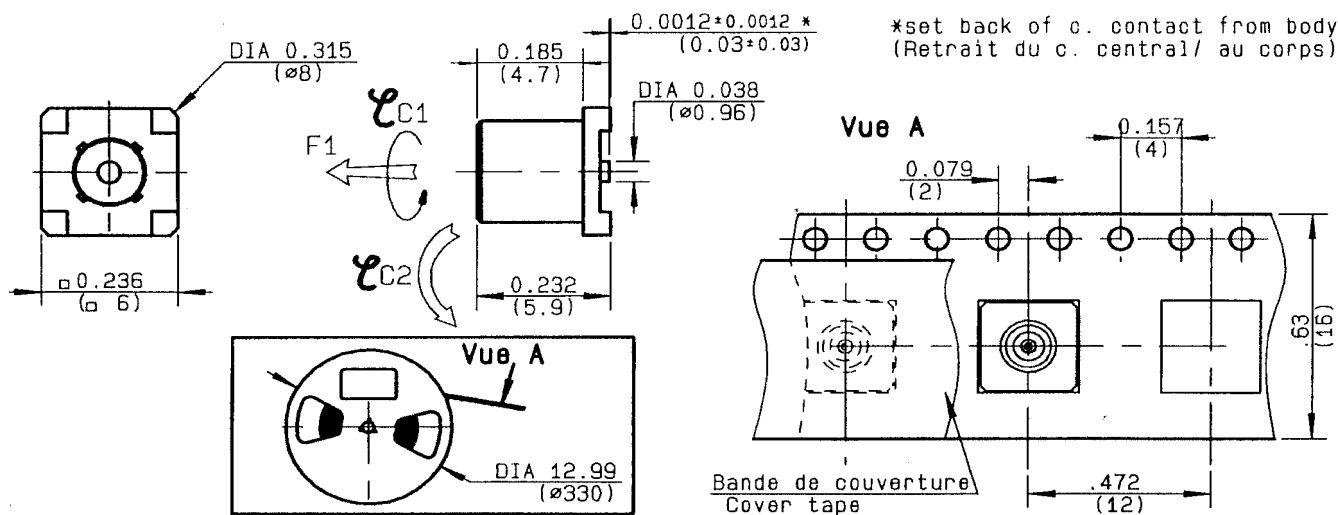


STRAIGHT FEMALE RECEPTACLE FOR PCB

SMT TYPE - REEL OF 500

R113.424.020

Series : MCX



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 0412 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



STRAIGHT FEMALE RECEPTACLE FOR PCB**R113.424.020****SMT TYPE - REEL OF 500**

Series : MCX

PACKAGING

Standard	Unit	Other
500	-	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-6	GHz
VSWR	1.05 + 0.050	x F(GHz) Maxi
Insertion loss	0.03	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	- (NA)	- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	1000	M Ω mini

ENVIRONMENTAL

Operating temperature	-55/+155	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHERS CHARACTERISTICS

Assembly instruction

Others :

Drawing page 1:

FORCE F1:90N-TORQUES C1:45Ncm-C2:80Ncm

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	10 N mini
Axial force – Opposite end	10 N mini
Torque	NA N.cm mini
Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm
Mating life	500 Cycles mini
Weight	0.600 g

Issue : 0412 D

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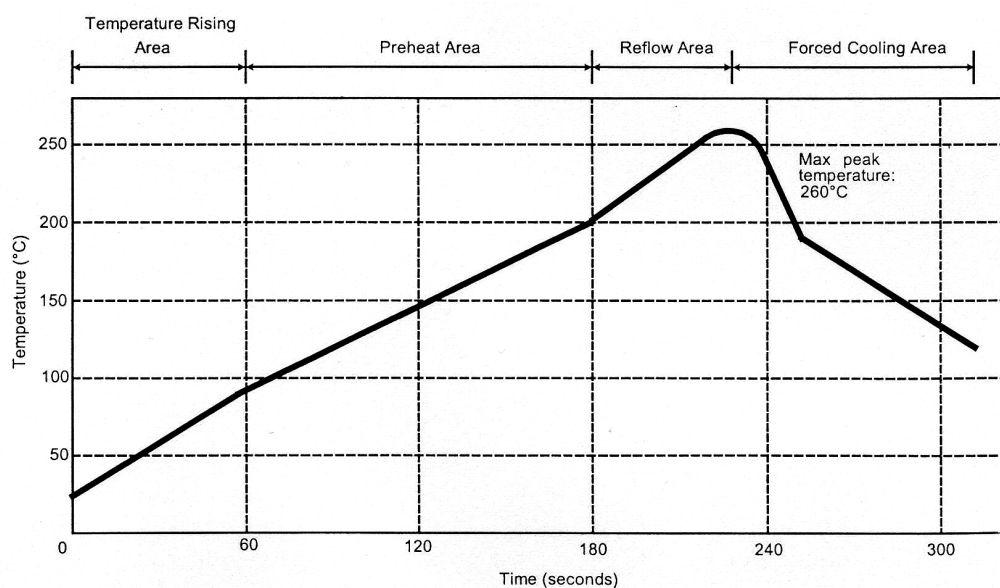


STRAIGHT FEMALE RECEPTACLE FOR PCB**SMT TYPE - REEL OF 500****R113.424.020**

Series : MCX

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux. We advise a thickness of 150 microns mini. (.006 inch mini).
Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Aspiration port (see page 4) centered into body and push against it.
A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below please find ,the typical profile to use.
4. Cleaning of printed circuit boards.
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFIL

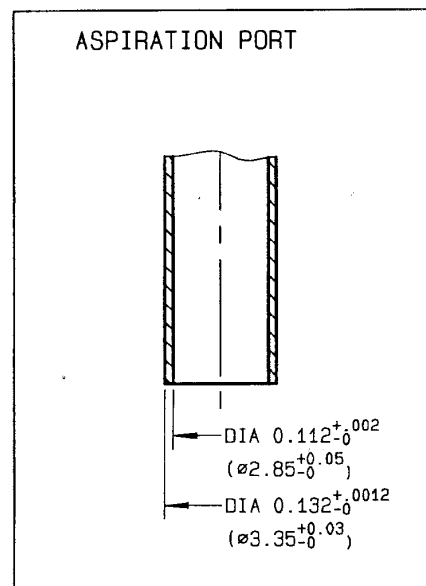
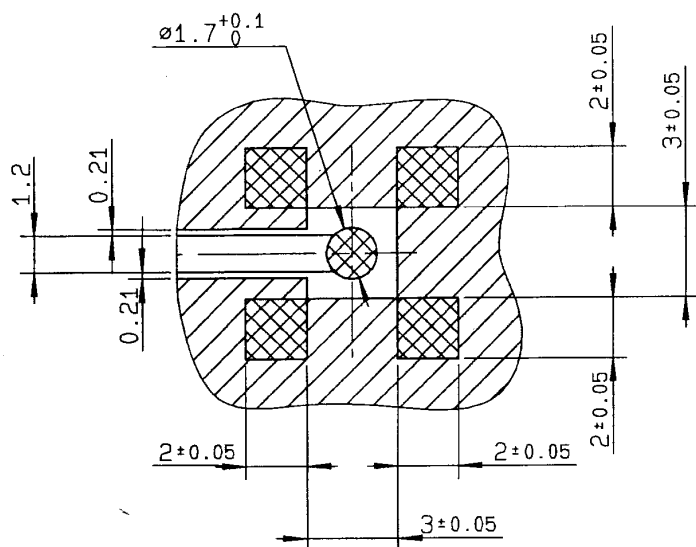
Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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R113.424.020

Series : **MCX**

The solder resist should be printed except for the land pattern on the PCB.



Pattern



Land for solder paste

0.235
(6)

0.235
(6)

DIA .316
(ø8.03)

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